

CA3045, CA3046

General Purpose NPN Transistor Arrays

November 1996

Features

•	Iwo Matched Transistors
	- $V_{\mbox{\footnotesize{BE}}}$ Match
	- I _{IO} Match 2μA (Max)

- Low Noise Figure 3.2dB (Typ) at 1kHz
- 5 General Purpose Monolithic Transistors
- Operation From DC to 120MHz
- Wide Operating Current Range
- Full Military Temperature Range

Applications

- Three Isolated Transistors and One Differentially Connected Transistor Pair for Low Power Applications at Frequencies from DC Through the VHF Range
- · Custom Designed Differential Amplifiers
- Temperature Compensated Amplifiers
- See Application Note, AN5296 "Application of the CA3018 Integrated-Circuit Transistor Array" for Suggested Applications

Description

The CA3045 and CA3046 each consist of five general purpose silicon NPN transistors on a common monolithic substrate. Two of the transistors are internally connected to form a differentially connected pair.

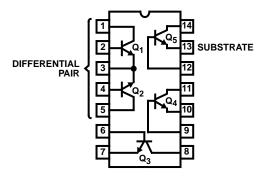
The transistors of the CA3045 and CA3046 are well suited to a wide variety of applications in low power systems in the DC through VHF range. They may be used as discrete transistors in conventional circuits. However, in addition, they provide the very significant inherent integrated circuit advantages of close electrical and thermal matching.

Ordering Information

PART NUMBER (BRAND)	TEMP. RANGE (°C)	PACKAGE	PKG. NO.	
CA3045	-55 to 125	14 Ld SBDIP	D14.3	
CA3045F	-55 to 125	14 Ld CERDIP	F14.3	
CA3046	-55 to 125	14 Ld PDIP	E14.3	
CA3046M (3046)	-55 to 125	14 Ld SOIC	M14.15	
CA3046M96 (3046)	-55 to 125	14 Ld SOIC Tape and Reel	M14.15	

Pinout

CA3045, (CERDIP, SBDIP) CA3046 (PDIP, SOIC) TOP VIEW



CA3045, CA3046

Absolute Maximum Ratings Thermal Information θ_{JA} (°C/W) θ_{JC} (°C/W) Thermal Resistance (Typical, Note 2) Collector-to-Base Voltage (V_{CBO}) 20V 180 N/A Collector-to-Substrate Voltage (V_{CIO}, Note 1) 20V CERDIP Package 150 75 125 60 220 N/A SOIC Package..... Maximum Power Dissipation (Any One Transistor) 300mW Maximum Junction Temperature (Hermetic Packages) 175°C **Operating Conditions** Maximum Junction Temperature (Plastic Package)150°C Temperature Range-55°C to 125°C Maximum Storage Temperature Range -65°C to 150°C Maximum Lead Temperature (Soldering 10s)............ 300°C (SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

- 1. The collector of each transistor of the CA3045 and CA3046 is isolated from the substrate by an integral diode. The substrate (Terminal 13) must be connected to the most negative point in the external circuit to maintain isolation between transistors and to provide for normal transistor action.
- 2. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications $T_A = 25^{\circ}C$, characteristics apply for each transistor in CA3045 and CA3046 as specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS	
DC CHARACTERISTICS								
Collector-to-Base Breakdown Voltage	V _(BR) CBO	$I_C = 10\mu A, I_E = 0$		20	60	-	V	
Collector-to-Emitter Breakdown Voltage	V _(BR) CEO	$I_C = 1 \text{mA}, I_B = 0$		15	24	-	V	
Collector-to-Substrate Breakdown Voltage	V _{(BR)CIO}	$I_C = 10\mu A, I_{CI} = 0$		20	60	-	V	
Emitter-to-Base Breakdown Voltage	V _{(BR)EBO}	$I_E = 10\mu A, I_C = 0$		5	7	-	V	
Collector Cutoff Current (Figure 1)	I _{CBO}	V _{CB} = 10V, I _E = 0		-	0.002	40	nA	
Collector Cutoff Current (Figure 2)	I _{CEO}	V _{CE} = 10V, I _B = 0		-	See Fig. 2	0.5	μΑ	
Forward Current Transfer Ratio (Static Beta)	h _{FE}	V _{CE} = 3V	I _C = 10mA	-	100	-	-	
(Note 3) (Figure 3)			I _C = 1mA	40	100	-	-	
			$I_C = 10\mu A$	-	54	-	-	
Input Offset Current for Matched Pair Q_1 and Q_2 . $ I_{ O1}$ - $I_{ O2} $ (Note 3) (Figure 4)		$V_{CE} = 3V$, $I_C = 1mA$		-	0.3	2	μΑ	
Base-to-Emitter Voltage (Note 3) (Figure 5)	V _{BE}	V _{CE} = 3V	I _E = 1mA	-	0.715	-	V	
			I _E = 10mA	-	0.800	-	V	
Magnitude of Input Offet Voltage for Differential Pair V _{BE1} - V _{BE2} (Note 3) (Figures 5, 7)		$V_{CE} = 3V$, $I_C = 1mA$		-	0.45	5	mV	
Magnitude of Input Offset Voltage for Isolated Transistors V _{BE3} - V _{BE4} , V _{BE4} - V _{BE5} , V _{BE5} - V _{BE3} (Note 3) (Figures 5, 7)		$V_{CE} = 3V$, $I_{C} = 1mA$		-	0.45	5	mV	
Temperature Coefficient of Base-to-Emitter Voltage (Figure 6)	$\frac{\Delta V}{\Delta T}$	$V_{CE} = 3V$, $I_{C} = 1mA$		-	-1.9	-	mV/ ^o C	
Collector-to-Emitter Saturation Voltage	V _{CES}	I _B = 1mA, I _C = 10mA		-	0.23	-	V	
Temperature Coefficient: Magnitude of Input Offset Voltage (Figure 7)	$\frac{\left \Delta V_{IO}\right }{\Delta T}$	$V_{CE} = 3V$, $I_{C} = 1mA$		-	1.1	-	μV/ ^o C	

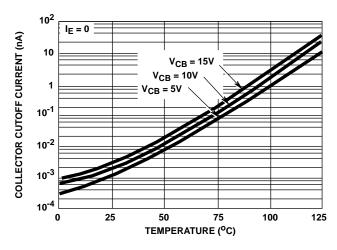
Electrical Specifications $T_A = 25^{\circ}C$, characteristics apply for each transistor in CA3045 and CA3046 as specified **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS		
DYNAMIC CHARACTERISTICS								
Low Frequency Noise Figure (Figure 9)	NF	$f = 1kHz$, $V_{CE} = 3V$, $I_{C} = 100\mu A$, Source Resistance = $1k\Omega$	-	3.25	-	dB		
Low Frequency, Small Signal Equivalent Circuit Characteristics								
Forward Current Transfer Ratio (Figure 11)	h _{FE}	$f = 1kHz$, $V_{CE} = 3V$, $I_{C} = 1mA$	-	110	-	-		
Short Circuit Input Impedance (Figure 11)	hIE	$f = 1kHz$, $V_{CE} = 3V$, $I_{C} = 1mA$	-	3.5	-	kΩ		
Open Circuit Output Impedance (Figure 11)	h _{OE}	f = 1kHz, V _{CE} = 3V, I _C = 1mA	-	15.6	-	μS		
Open Circuit Reverse Voltage Transfer Ratio (Figure 11)	h _{RE}	$f = 1kHz$, $V_{CE} = 3V$, $I_{C} = 1mA$	-	1.8 x 10 ⁻⁴	-	-		
Admittance Characteristics								
Forward Transfer Admittance (Figure 12)	Y_{FE}	$f = 1kHz$, $V_{CE} = 3V$, $I_{C} = 1mA$	-	31 - j1.5	-	-		
Input Admittance (Figure 13)	Y _{IE}	f = 1kHz, V _{CE} = 3V, I _C = 1mA	-	0.3 + j0.04	-	-		
Output Admittance (Figure 14)	Y _{OE}	$f = 1kHz$, $V_{CE} = 3V$, $I_{C} = 1mA$	-	0.001 + j0.03	-	-		
Reverse Transfer Admittance (Figure 15)	Y _{RE}	$f = 1kHz$, $V_{CE} = 3V$, $I_{C} = 1mA$	-	See Fig. 14	-	-		
Gain Bandwidth Product (Figure 16)	f _T	$V_{CE} = 3V$, $I_C = 3mA$	300	550	-	MHz		
Emitter-to-Base Capacitance	C _{EB}	$V_{EB} = 3V, I_{E} = 0$	-	0.6	-	pF		
Collector-to-Base Capacitance	C _{CB}	$V_{CB} = 3V, I_{C} = 0$	-	0.58	-	pF		
Collector-to-Substrate Capacitance	C _{CI}	$V_{CS} = 3V, I_{C} = 0$	-	2.8	-	pF		

NOTE:

3. Actual forcing current is via the emitter for this test.

Typical Performance Curves



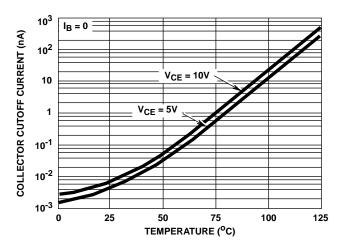


FIGURE 1. TYPICAL COLLECTOR-TO-BASE CUTOFF CURRENT vs TEMPERATURE FOR EACH TRANSISTOR

FIGURE 2. TYPICAL COLLECTOR-TO-EMITTER CUTOFF CURRENT vs TEMPERATURE FOR EACH TRANSISTOR

Typical Performance Curves (Continued)

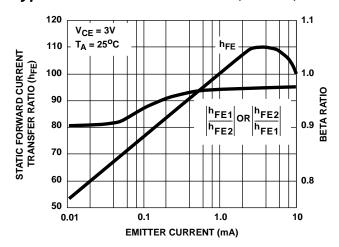


FIGURE 3. TYPICAL STATIC FORWARD CURRENT TRANSFER RATIO AND BETA RATIO FOR \mathbf{Q}_1 AND \mathbf{Q}_2 vs EMITTER CURRENT

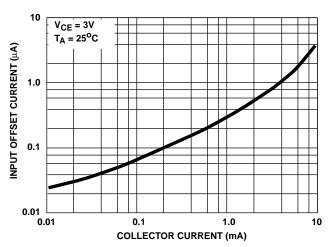


FIGURE 4. TYPICAL INPUT OFFSET CURRENT FOR MATCHED TRANSISTOR PAIR $\mathbf{Q_1Q_2}$ vs COLLECTOR CURRENT

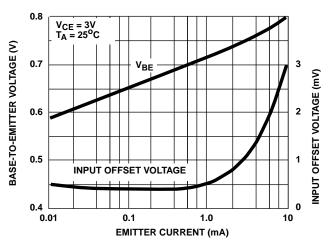


FIGURE 5. TYPICAL STATIC BASE-TO-EMITTER VOLTAGE
CHARACTERISTICS AND INPUT OFFSET VOLTAGE
FOR DIFFERENTIAL PAIR AND PAIRED ISOLATED
TRANSISTORS vs EMITTER CURRENT

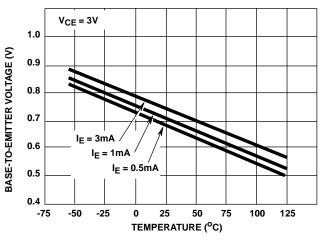


FIGURE 6. TYPICAL BASE-TO-EMITTER VOLTAGE
CHARACTERISTIC vs TEMPERATURE FOR EACH
TRANSISTOR

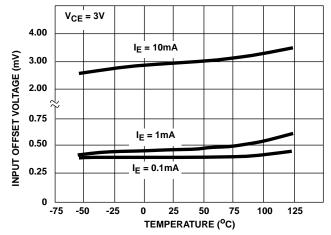


FIGURE 7. TYPICAL INPUT OFFSET VOLTAGE CHARACTERISTICS FOR DIFFERENTIAL PAIR AND PAIRED ISOLATED TRANSISTORS vs TEMPERATURE

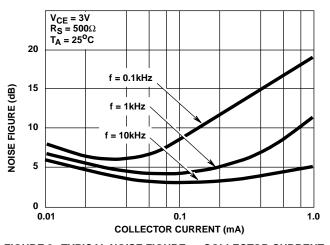
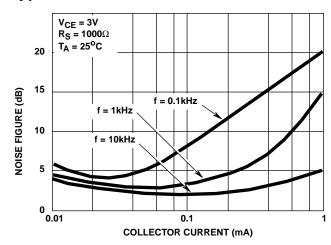


FIGURE 8. TYPICAL NOISE FIGURE vs COLLECTOR CURRENT

Typical Performance Curves (Continued)



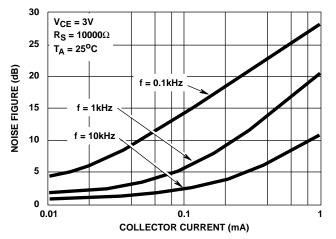
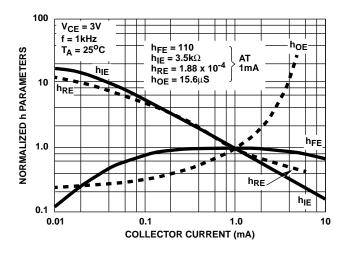


FIGURE 9. TYPICAL NOISE FIGURE vs COLLECTOR CURRENT

FIGURE 10. TYPICAL NOISE FIGURE vs COLLECTOR CURRENT



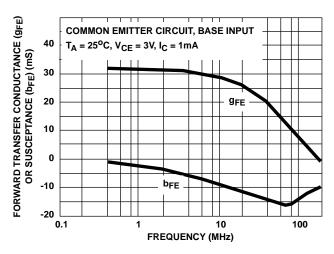
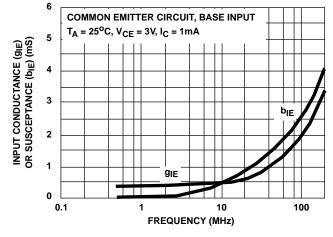


FIGURE 11. TYPICAL NORMALIZED FORWARD CURRENT
TRANSFER RATIO, SHORT CIRCUIT INPUT
IMPEDANCE, OPEN CIRCUIT OUTPUT IMPEDANCE,
AND OPEN CIRCUIT REVERSE VOLTAGE TRANSFER
RATIO vs COLLECTOR CURRENT

FIGURE 12. TYPICAL FORWARD TRANSFER ADMITTANCE vs FREQUENCY



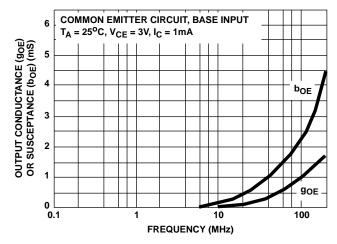
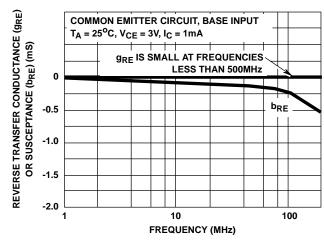


FIGURE 13. TYPICAL INPUT ADMITTANCE vs FREQUENCY

FIGURE 14. TYPICAL OUTPUT ADMITTANCE vs FREQUENCY

Typical Performance Curves (Continued)



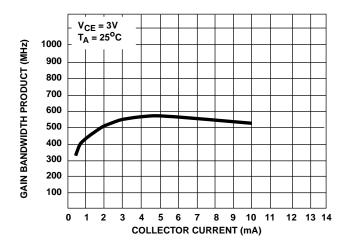


FIGURE 15. TYPICAL REVERSE TRANSFER ADMITTANCE vs FREQUENCY

FIGURE 16. TYPICAL GAIN BANDWIDTH PRODUCT vs COLLECTOR CURRENT

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